

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 08/26/2022

Details for "SN75C1154N"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN75C1154N	NIPDAU	Level-NC-NC-NC	TI MALAYSIA A/T	N 20	6.35x24.33x4.57	1679.9

***Total Device Mass**

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	No	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Iron	7439-89-6	0.000001	0.000306	3	0	0
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000001	0.000306	3	0	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000002	0.000611	6	0	0
Precious Metals	Gold	7440-57-5	0.327124	99.997555	999976	0.019473	195
Precious Metals	Silver	7440-22-4	0.000004	0.001223	12	0	0
Sub-Total			0.327132	100	1000000	0.019473	195
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.659686	69.999968	700000	0.039269	393
Thermoplastics	Epoxy	85954-11-6	0.282723	30.000032	300000	0.01683	168
Sub-Total			0.942409	100	1000000	0.056098	561
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	373.891957	97.701	977010	22.256521	222565
Copper and Its Alloys	Iron	7439-89-6	8.189566	2.14	21400	0.487497	4875
Copper and Its Alloys	Phosphorus	7723-14-0	0.126288	0.033	330	0.007517	75
Zinc and Its Alloys	Zinc	7440-66-6	0.482189	0.126	1260	0.028703	287
Sub-Total			382.69	100	1000000	22.780239	227802
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	29.496712	95.12	951200	1.755839	17558
Precious Metals	Gold	7440-57-5	0.241878	0.78	7800	0.014398	144
Precious Metals	Palladium	7440-05-3	1.27141	4.1	41000	0.075683	757
Sub-Total			31.01	100	1000000	1.84592	18459
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	899.124732	71.3	713000	53.521849	535218
Other Nonferrous Metals and Alloys	Antimony Trioxide	1309-64-4	5.044178	0.4	4000	0.300263	3003
Other Organic Materials	Brominated Epoxy	40039-93-8	25.22089	2	20000	1.501314	15013
Other Plastics and Rubber	Carbon Black	1333-86-4	3.657029	0.29	2900	0.217691	2177
Thermoplastics	Epoxy	85954-11-6	327.997676	26.01	260100	19.52459	195246
Sub-Total			1261.044505	100	1000000	75.065707	750657
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	3.906867	100	1000000	0.232563	2326
Sub-Total			3.906867	100	1000000	0.232563	2326
Total			1679.920913			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.